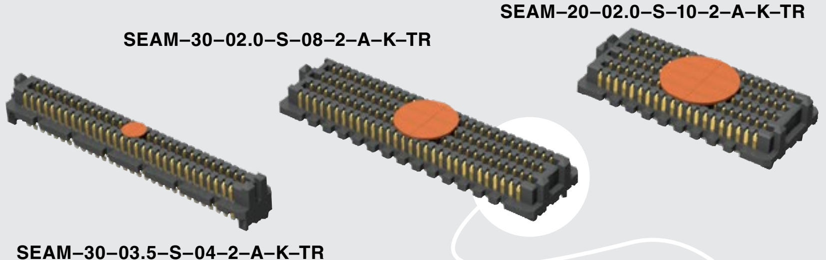
F-219 (Rev 19AUG20)

samtec

SEARAY™



(1.27 mm) .050"

SEAM SERIES

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Operating Temp Range:
-55 °C to +125 °C
Current Rating (7 mm stack height):
2.7 A per pin
(10 adjacent pins powered)
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Working Voltage:
240 VAC
RoHS Compliant:
Yes (–2 Solder type only)
Lead-Free Solderable:
Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

Visit www.samtec.com/standards for more information.

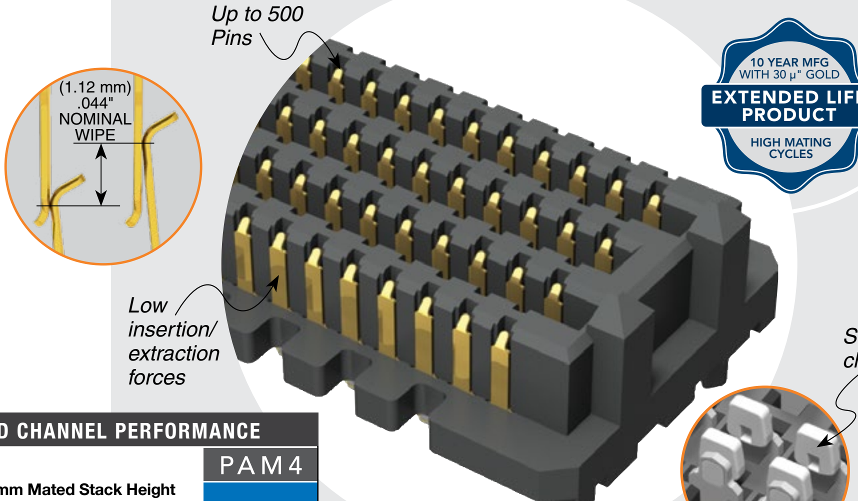
MATED HEIGHTS				
SEAM LEAD STYLE	SEAF LEAD STYLE			
	–05.0	–06.0	–06.5	–07.5
–02.0	7 mm	8 mm	8.5 mm	9.5 mm
–03.0	8 mm	9 mm	9.5 mm	10.5 mm
–03.5	8.5 mm	9.5 mm	10 mm	11 mm
–06.5	11.5 mm	12.5 mm	13 mm	14 mm
–07.0	12 mm	13 mm	13.5 mm	14.5 mm
–09.0	14 mm	15 mm	15.5 mm	16.5 mm
–11.0	16 mm	17 mm	17.5 mm	18.5 mm

Notes:
IPC-A-610F & IPC-J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

Mates with:
SEAF, SEAFP

Standoffs:
JSO



10 YEAR MFG WITH 30 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

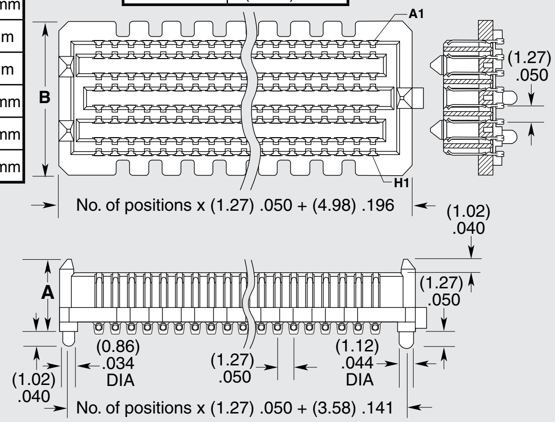
PAM4
56
Gbps

OTHER SOLUTIONS

- Up to 560 pins

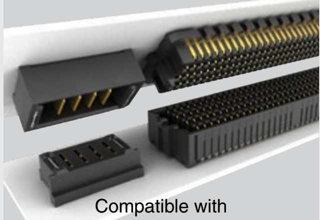
SEAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	"X"R
	–10, –15, –20, –30, –40, –50 (–10 only available in 04 row) (–15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style)	Specify LEAD STYLE from chart	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail **–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on solder tail	**–04** =Four Rows (–06.5 not available) **–05** =Five Rows (–06.5 not available) **–06** =Six Rows (–06.5 not available) **–08** =Eight Rows **–10** =Ten Rows	**–1** = Tin/Lead Alloy Solder Charge **–2** = Lead-Free Solder Charge	**–A** = Alignment Pins (Required. Arrays will not self-center on solder pads) **–K** = Polyimide film Pick & Place Pad **–TR** =Tape & Reel **–FR** = Full Reel Tape & Reel Packaging (Must order max. quantities per reel. Contact Samtec for parts per reel)		

NO. OF ROWS	B
–04	(7.06) .278
–05, –06	(9.60) .378
–08	(12.14) .478
–10	(14.68) .578



LEAD STYLE	A
–02.0	(5.61) .221
–03.0	(6.60) .260
–03.5	(7.11) .280
–06.5	(10.16) .400
–07.0	(10.59) .417
–09.0	(12.60) .496
–11.0	(14.61) .575

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions